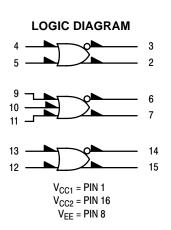
Triple 2-3-2-Input OR/NOR Gate

The MC10105 is a triple 2-3-2 input OR/NOR gate.

- $P_D = 30 \text{ mW typ/gate (No Load)}$
- $t_{pd} = 2.0 \text{ ns typ}$
- t_r , $t_f = 2.0$ ns typ (20%–80%)

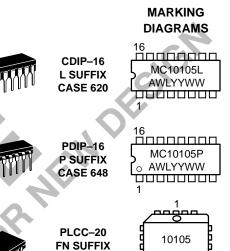


DIP **PIN ASSIGNMENT** V_{CC1} 16 V_{CC2} c_{out} 2 A_{OUT} 15 C_{OU}T A_{OUT} 3 14 13 C_{IN} A_{IN} 4 A_{IN} 5 12 B_{OUT} $\mathsf{B}_{\mathsf{OUT}}$ B_{IN} 10 V_{EE} B_{IN}

Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



http://onsemi.com



AWLYYWW

A = Assembly Location

CASE 775

WL = Wafer Lot YY = Year

WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10105L	CDIP-16	25 Units / Rail
MC10105P	PDIP-16	25 Units / Rail
MC10105FN	PLCC-20	46 Units / Rail

ELECTRICAL CHARACTERISTICS

		_	Test Limits							
		Pin Under	-30	0°C		+25°C		+85	5°C	
Characteristic	Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Uni
Power Supply Drain Current	Ι _Ε	8		23		17	21		23	mAc
Input Current	I _{inH}	4		425			265		265	μAd
	I _{inL}	4	0.5		0.5			0.3		μAd
Output Voltage Logic 1	V _{OH}	3 2	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	Vdd
Output Voltage Logic 0	V _{OL}	3 2	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	Vdd
Threshold Voltage Logic 1	V _{OHA}	3 2	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		Vdo
Threshold Voltage Logic 0	V _{OLA}	3 2		-1.655 -1.655			-1.630 -1.630		-1.595 -1.595	Vd
Switching Times (50Ω Load)										ns
Propagation Delay	t ₄₊₃ - t ₄₋₃₊ t ₄₊₂₊ t ₄₋₂ -	3 3 2 2	1.0 1.0 1.0 1.0	3.1 3.1 3.1 3.1	1.0 1.0 1.0 1.0	2.0 2.0 2.0 2.0	2.9 2.9 2.9 2.9	1.0 1.0 1.0 1.0	3.3 3.3 3.3 3.3	
Rise Time (20 to 80%)	t ₃₊ t ₂₊	3 2	1.1 1.1	3.6 3.6	1.1 1.1	2.0 2.0	3.3 3.3	1.1 1.1	3.7 3.7	
Fall Time (20 to 80%)	t ₃₋ t ₂₋	3 2	1.1 1.1	3.6 3.6	1.1 1.1	2.0 2.0	3.3 3.3	1.1 1.1	3.7 3.7	
	•	9		NO	O					

ELECTRICAL CHARACTERISTICS (continued)

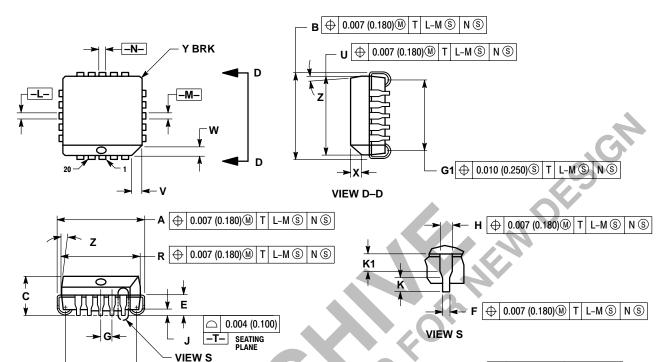
				TEST VOLTAGE VALUES (Volts)					
		@ Test Te	mperature	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	
	–30°C				-1.890	-1.205	-1.500	-5.2	ļ
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
			Pin	TEST V	OLTAGE AP	PLIED TO P	NS LISTED I	BELOW	
Characteri	istic	Symbol	Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	(V _{CC}) Gnd
Power Supply Drain (Current	ΙE	8					8	1, 16
Input Current		l _{inH}	4	4				8	1, 16
		I _{inL}	4		4			8	1, 16
Output Voltage	Logic 1	V _{OH}	3 2	4				8 8	1, 16 1, 16
Output Voltage	Logic 0	V _{OL}	3 2	4				8	1, 16 1, 16
Threshold Voltage	Logic 1	V _{OHA}	3 2			4	4	8 8	1, 16 1, 16
Threshold Voltage	Logic 0	V _{OLA}	3 2			4	4	8 8	1, 16 1, 16
Switching Times	(50Ω Load)					Pulse In	Pulse Out	−3.2 V	+2.0 V
Propagation Delay		t ₄₊₃₋ t ₄₋₃₊ t ₄₊₂₊ t ₄₋₂₋	3 3 2 2			4 4 4 4	3 3 2 2	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Rise Time	(20 to 80%)	t ₃₊ t ₂₊	3 2			4 4	3 2	8 8	1, 16 1, 16
Fall Time	(20 to 80%)	t ₃₋ t ₂₋	3 2			4 4	3 2	8 8	1, 16 1, 16

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to –2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF MICE. NOT PERSON

- OTES:

 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

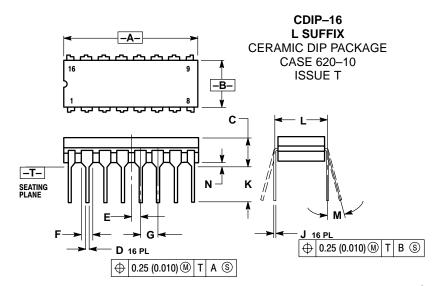
 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 4. DIMENSIONING AND TOLERANCING PER ANSI V14 5M 1982
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

PACKAGE DIMENSIONS



NOTES:

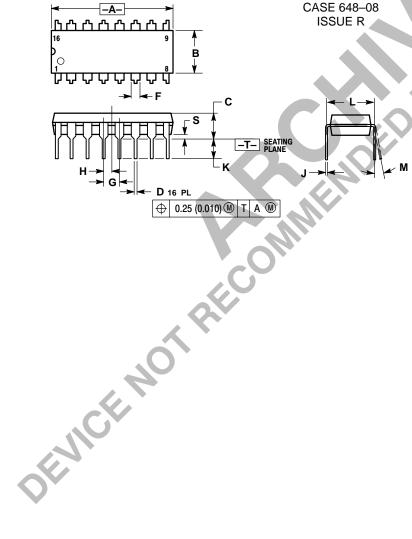
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

 DIMENSION F MAY NARROW TO 0.76 (0.030)
 WHERE THE LEAD ENTERS THE CERAMIC
 BODY.

	INC	HES	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
Α	0.750	0.785	19.05	19.93		
В	0.240	0.295	6.10	7.49		
C		0.200		5.08		
D	0.015 0.020		0.39	0.50		
E	0.050	BSC	1.27 BSC			
F	0.055	0.065	1.40	1.65		
G	0.100	BSC	2.54	BSC		
Н	0.008	0.015	0.21	0.38		
K	0.125	0.170	3.18	4.31		
L	0.300	BSC	7.62	BSC		
M	0 °			15°		
N	0.020	0.040	0.51	1.01		

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIMETERS			
DIM	MIN MAX		MIN	MAX		
Α	0.740	0.770	18.80	19.55		
В	0.250	0.270	6.35	6.85		
С	0.145	0.175	3.69	4.44		
D	0.015	0.021	0.39	0.53		
F	0.040	0.70	1.02	1.77		
G	0.100	BSC	2.54 BSC			
Н	0.050	BSC	1.27	BSC		
J	0.008	0.015	0.21	0.38		
K	0.110	0.130	2.80	3.30		
L	0.295	0.305	7.50	7.74		
M	0°	10 °	0°	10 °		
S	0.020	0.040	0.51	1.01		

Notes



Notes





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